

1. (amended) An electronic component comprising:  
an electronic device package including a silicon wafer having a recess,  
the recess including a conductive region; and  
a bare die electronic device having a top, a bottom, sides, and a plurality  
of terminals, including a non-top terminal, the device being disposed in the  
recess, and wherein the non-top terminal is electrically coupled to the  
conductive region.

9. (twice amended) An electronic component according to claim 1,  
wherein the device is a vertical device and the bottom of the device is coupled  
to the recess.

14. (twice amended) An electronic component comprising:  
an electronic component package including a silicon wafer having a  
recess, the recess including a first conductive region; and  
a bare die electronic device having a top, a bottom, sides, and a plurality  
of terminals, including a non-top terminal and a top terminal, the device being  
disposed in the recess, wherein the non-top terminal is electrically coupled to  
the first conductive region and the top terminal is electrically coupled to a  
second conductive region, and wherein at least a portion of the first and second  
conductive regions are essentially planar.

16. (amended) An electronic component comprising:  
an electronic device package including a silicon wafer having a recess,  
the recess including a conductive region; and

an electronic device having a top, a bottom, sides, and a plurality of terminals, including a non-top terminal located in a region other than the top of the device, the device being disposed in the recess, wherein the non-top terminal is electrically coupled to the conductive region.

21. (amended) An electronic component comprising:

an electronic device having a first terminal and a second terminal, wherein a first dimension is defined therebetween;

an electronic device package having a first surface, the package including a silicon wafer having a recess on the first surface that has a depth that is substantially equal to the first dimension, the package further having a layer of metal applied to the recess and to a portion of the first surface, wherein the electronic device resides within the recess and the second terminal is coupled to the layer of metal; and

a layer of insulation coupling the electronic device to the silicon wafer.

22. (amended) An electronic component according to claim 21, further comprising:

a first contact coupled to the first terminal; and

a second contact coupled to the metal residing on the first surface of the package.

32. (amended) An electronic component comprising:

a non-molded electronic component package having a package top and a silicon wafer including a recess;